



IPFW

IN 10/775,890

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	Biswajit Sur et al.	Examiner:	Andy Huynh
Serial No.:	10/775,890	Group Art Unit:	2818
Filed:	February 9, 2004	Docket No.:	884.319US2
Title:	ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE AND METHODS OF MANUFACTURE		
Assignee:	Intel Corporation	Customer No:	21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on October 19, 2004. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office action, thereby moving the deadline for response from January 19, 2005 to February 19, 2005. Since February 19, 2005 falls on a Saturday, and Monday, February 21, 2005 is a federal holiday, it is believed that the due date carries over to the next business day, Tuesday, February 22, 2005.